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DOCKET 99-102/1D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Wilbur G. Catabay and Richard Schinella	JN 10 JN 10 Logy C
Filed: March 15, 2002	2002 ENTE
Serial Number: 10/099,641	Group Art Unit: Unknown
Title: "Low k Dielectric Composite Layer for Integrated Circuit Structure Which Provides Void-Free Low k) Examiner: Unknown)
Dielectric Material Between Metal Lines While Mitigating Via Poisoning")
	<i>)</i>

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.56

Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

Sir:

Pursuant to 37 CFR 1.56, 1.97, and 1.98, Applicants submit the attached form PTO-1449 (modified). This application is a 37 C.F.R. 1.53(b) divisional application of Serial No. 09/426,056. Since the document listed on the enclosed form PTO-1449 (modified) was previously cited to or by the USPTO in the prior application, under the provisions of 37 C.F.R. 1.98(d), a copy of the listed document is not enclosed.

Respectfully submitted,

John P. Taylor

Attorney for Applicant Registration No. 22,369

Date: May 21, 2002

(909) 699-7551

Mailing Address:

Sandeep Jaggi, Chief Intellectual Property Counsel Intellectual Property Law Department LSI Logic Corporation Mail Stop D-106 Milpitas, CA 95035 JUN 0 5 2002 & LSI LOGIC 99-102/1D

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wilbur G. Catabay and Richard Schinella

Serial No.: 10/099,641

Group Art Unit: Unknown

Filed: March 15, 2002

Examiner: Unknown

For: LOW k

LOW K DIELECTRIC COMPOSITE LAYER FOR INTEGRATED CIRCUIT STRUCTURE

WHICH PROVIDES VOID-FREE LOW K DIELECTRIC MATERIAL BETWEEN METAL

LINES WHILE MITIGATING VIA POISONING

Assistant Commissioner for Patents Washington, D.C. 20231

Date: May 21, 2002

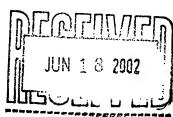
TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT

⊠	WITHIN THREE MONTHS OF (37 C.F.R. 1.97(b))	FILING OR BEFORE MAILING OF FIRST OFFICE	ACTION		
	BEFORE MAILING DATE OF EITHER A FINAL ACTION OR NOTICE OF ALLOWANCE (37 C.F.R. 1.97(c))				
	AFTER MAILING DATE OF FINAL ACTION OR NOTICE OF ALLOWANCE BUT BEFORE PAYMENT OF ISSUE FEE (37 C.F.R. 1.97(d))				

Pursua PTO-1	449 (modified). Copies of each of	CHRC			
	CENTIFIC	CATE OF MAILING/TRANSMISSION	是 四		
l hereby ce	rtify that this correspondence is, on the date shown	below, being:	1000		
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envelope ad	Idressed to the Assistant Commissioner				
ior ratents,	, Washington, D.C. 20231.	John & Janka			
Date: <u>N</u>	May 21, 2002	Signature	•		
		John P. Taylor			
		(Type or print name of person certifying)	-		

I. TIME OF TRANSMITTAL OF ACCOMPANYING INFORMATION DISCLOSURE STATEMENT

A.	×	THIS INFORMATION DISCLOSURE STATEMENT IS SUBMITTED WITHIN THREE MONTHS OF FILING OR BEFORE MAILING OF FIRST OFFICE ACTION (37 C.F.R. 1.97(b)).
		The information disclosure statement transmitted herewith is being filed:
		(1) Within three months of the filing date of a national application.
		(2) Within three months of the date of entry of the national stage as set forth in § 1.491 in an international application.
		(3) Before the mailing date of a first Office Action on the merits.
		(4) To the best of the undersigned's knowledge, the information disclosure statement submitted herewith is being filed before the mailing date of a first Office action on the merits under 37 C.F.R. 1.97(b)(3). However, in the event that the USPTO has mailed an Office Action not yet received by the undersigned, a statement under 37 C.F.R. 1.97(e) is enclosed, since the disclosures submitted herewith were received by Applicants less than three months prior to the mailing date of this submittal.
В.		THIS INFORMATION DISCLOSURE STATEMENT IS SUBMITTED BEFORE MAILING DATE OF EITHER A FINAL ACTION OR NOTICE OF ALLOWANCE 37 C.F.R. 1.97(c)).
		The information disclosure statement transmitted herewith is being filed before the nailing date of either a final action under § 1.113 or a notice of allowance under 1.311, whichever occurs first, and is accompanied by either:
		(1) a statement as specified in 37 C.F.R. 1.97(e).
		(2) the fee set forth in 37 C.F.R. 1.17(p) for submission of an information disclosure statement under § 1.97(c). (\$240.00).



· C.		THIS INFORMATION DISCLOSURE STATEMENT IS SUBMITTED AFTER MAILING DATE OF FINAL ACTION OR NOTICE OF ALLOWANCE BUT BEFORE PAYMENT OF ISSUE FEE (37 C.F.R. 1.97(d)).
		The information disclosure statement transmitted herewith is being filed <i>after</i> a final action under § 1.113, or a notice of allowance under § 1.311, whichever occurs first but before, or simultaneously with, the payment of the issue fee.
		In accordance with the requirements of 37 C.F.R. 1.97(d):
		(1) Accompanying this transmittal is a statement as specified in 37 C.F.R. 1.97(e).
		(2) Applicant hereby petitions for the consideration of the accompanying information disclosure statement under 37 C.F.R. 1.97(d)(2).
		☐ (3) Applicant submits the petition fee set forth in § 1.17(i) (\$130.00).
п. 🗆	STA 1.97	TEMENT FOR INFORMATION DISCLOSURE UNDER 37 C.F.R. §
II. 🗆	1.97	
II. 🗆	1.97	(e)
II.	1.97	person(s) signing below state: (1) that each item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure

III.	FEE DUE		
	Ø	No Fee due under 37 C.F.R. 1.97(b).	
		Fee under 37 C.F.R. 1.97(c) \$240.00 (37 C.F.R. 1.17(p)).	
		Petition fee under 37 C.F.R. 1.97(d) \$130.00 (37 C.F.R. 1.17(i)).	
IV.	METI	HOD OF PAYMENT OF FEE	
		Attached is a check for \$	
		Charge Account 20-0092 \$	
	If any a	additional fees are due, please charge Account 20-0092.	
		Signature of Practitioner John P. Taylor (Type or print name of practitioner) Attorney for Applicants	
		Registration No. 22,369 Telephone No. (909) 699-7551	
Mailing	Address		
c/o Intel LSI Log Mail Sto 1551 Mc Milpitas	ic Corpo p D-106 :Carthy I	Blvd.	

Page 4 of 4